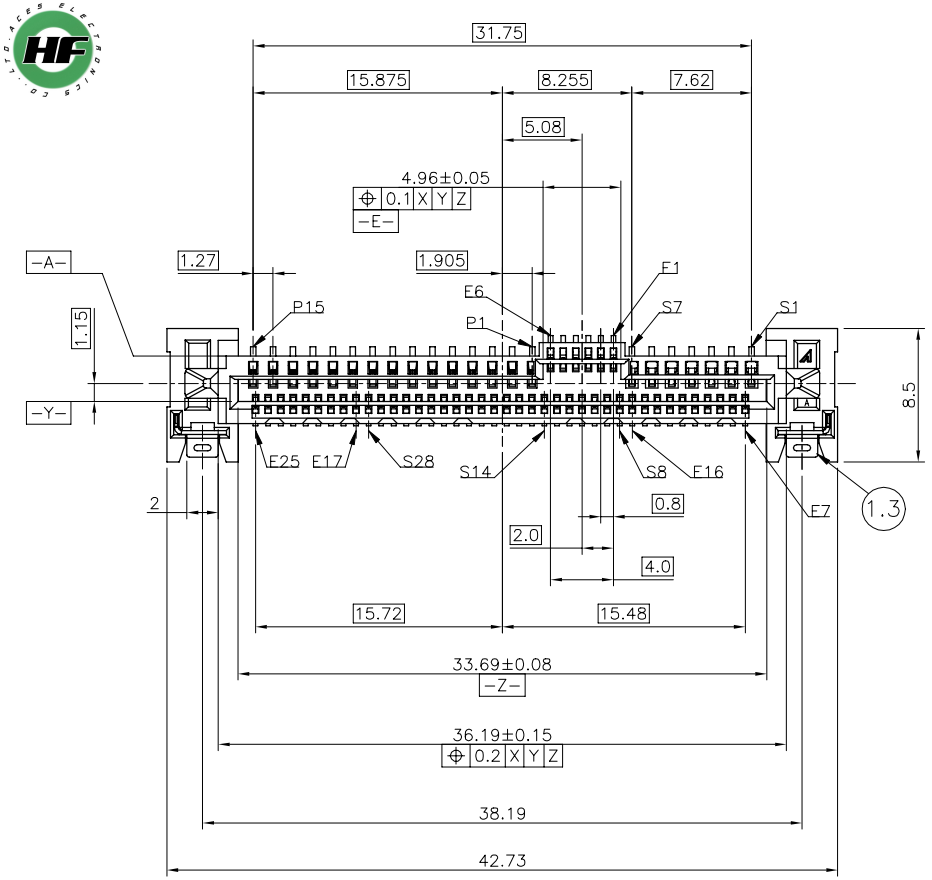
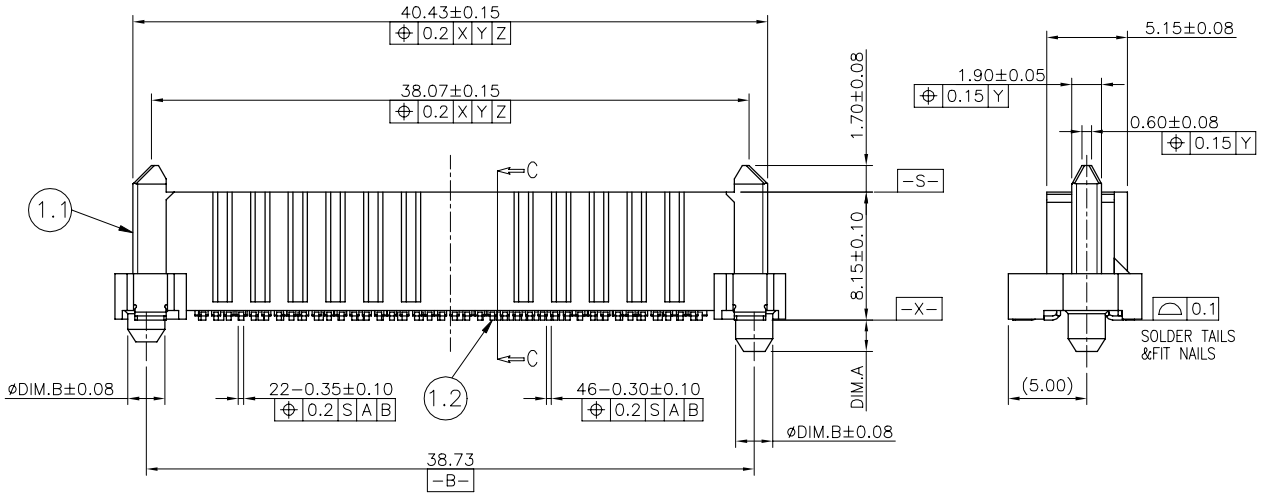




NOTES:
1. MATERIAL:
   1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0; COLOR:BLACK.
   1.2 CONTACT: COPPER ALLOY
   1.3 FIT NAIL: COPPER ALLOY
2. FINISH:
   2.1 CONTACT:
   100~200u" MATTE TIN PLATING ON SOLDER TAILS.
   50~100u" NICKEL UNDERPLATING OVERALL.
   (C) 15u" GOLD PLATING ON CONTACT AREA
   2.2 FIT NAIL:
   100~200u" MATTE TIN PLATING ON SOLDER TAILS.
   50~100u" NICKEL UNDERPLATNG OVERALL.
3. SUPPORT PCIe Gen4 AND SAS3.
4. REFLOW SOLDER CAPABLE TO 260°C ,PER ACES SPEC.
5. SPEC. PLS. REFER TO PS-52961-XXXXX-XXX
6. PACKAGE PLS. REFER TO 52960-XXXXX-XX-TRP
7. PART NUMBER

52961-068 X X-XXX
- NO OF CKT: XXX.CKT
- PACKING: 0: TAPE&REEL
- PLATING: C: 15u" GOLD PLATING ON CONTACT AREA
- TYPE: 001: PLS. SEE TABLE

PART NO.	DIM. A	DIM. B	DIM. C
52961-068xx-001	2.00	φ2.36	φ2.50

QUALITY SYMBOLS
MAJOR (M)
CRITICAL (C)

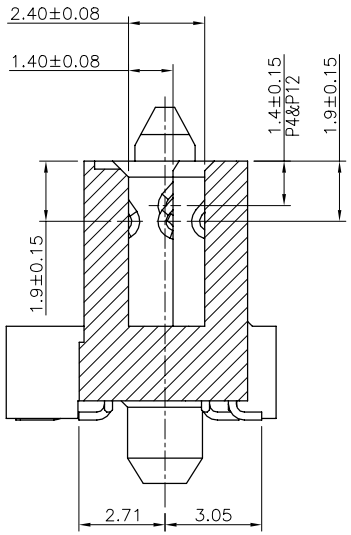
GENERAL TOLERANCES (UNLESS SPECIFIED)
X. ±0.5
.X ±0.25
.XX ±0.15
.XXX ±0.1
ANGLES ±2°

DRAWN BY	Lin, Chia Ann	DATE 22'/03/22
CHECKED BY	Lee, I Hung	DATE 22'/03/22
APPROVED BY	Wang, Chun Sheng	DATE 22'/03/22

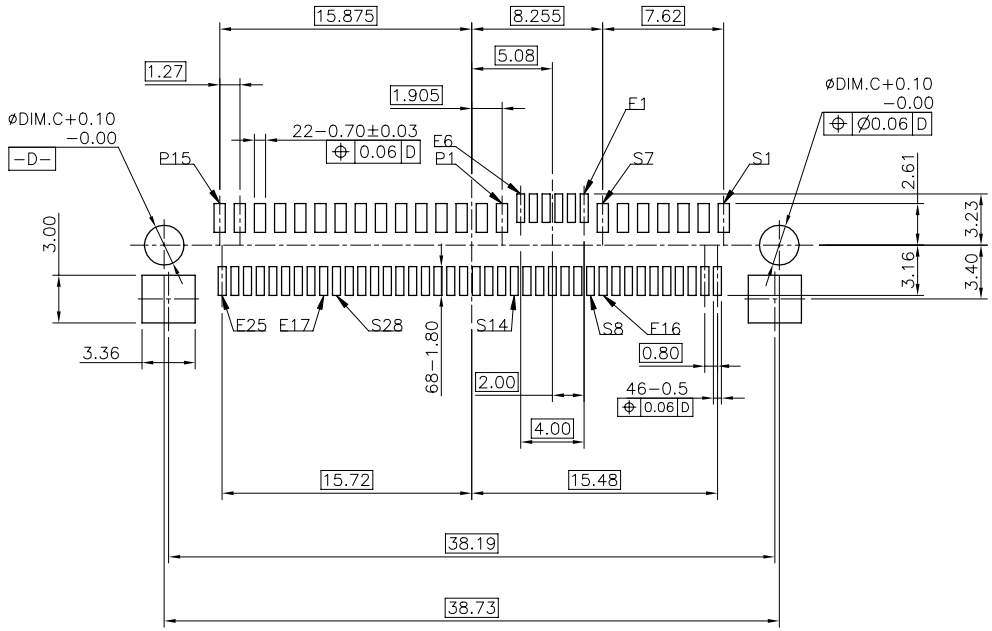
ACES ELECTRONICS

TITLE: 1.27/0.8 PITCH SAS+PCIE RECEPTACLE VERTICAL SMT TYPE

UNITS	SIZE	RFQ NO.
mm	A4	N/A
SCALE 2 : 1	SHEET NO. 1 OF 2	REV A
		DWG NO. 52961-068XX-XXX



SECTION C–C
SCALE 4:1



RECOMMENDED P.C.B. LAYOUT

QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓒ GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY: Lin, Chia Ann — DATE: 22/03/22 CHECKED BY: Lee, I Hung — DATE: 22/03/22 APPROVED BY: Wang, Chun Sheng — DATE: 22/03/22 UNITS: mm SCALE: 2 : 1 SHEET NO.: 2 OF 2	ACES ELECTRONICS TITLE: 1.27/0.8 PITCH SAS+PCIE RECEPTACLE VERTICAL SMT TYPE SIZE: A4 RFQ NO.: N/A REV: A DWG NO.: 52961-068XX-XXX	